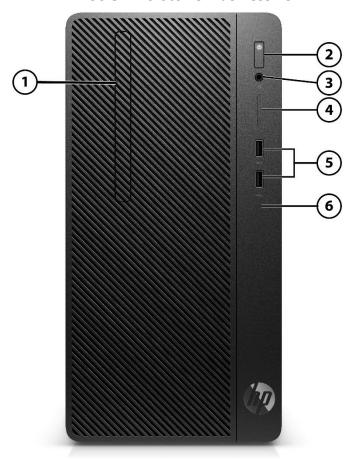
Overview

HP 290 G2 Microtower Business PC



Front

- 1. Slim-height Bay supporting an optical disk drive (optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. SD Card Reader
- 5. (2) USB 3.1 Gen1 Port
- 6. HDD LED Light

Not Shown

Slots (1) PCI Express x16

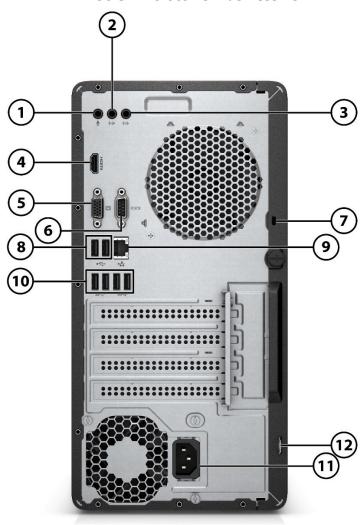
- (1) PCI Express x1
- (1) Legacy PCI (Optional)
- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage

Bays (1) 3.5" internal HDD bay

- (1) 3.5" or 2.5" internal HDD bay (share bay)
- (1) 9.5mm internal optical drive bay

Overview

HP 290 G2 Microtower Business PC



Back

- 1. Audio Mic in
- 2. Audio Line out
- 3. Audio Link in
- 4. HDMI Port1
- 5. VGA Port1
- 6. Serial Port (optional, and available on legacy PCA only)
- 7. Standard lock slot
- 8. (2) USB 2.0 port
- 9. RJ-45 Network Connector
- 10. (2) USB 3.1 Gen1 Port (left) and (2) USB 2.0 port (right)
- 11. Power Cord Connector
- 12. Padlock Loop

Not Shown

- (1) PS/2 Port (optional, and available on legacy PCA only)
- (2) Parallel Port (Optional via PCIex1 slot)
- (3) 4 Serial Port (Optional via PCIe slot)
- 1. Port will be covered up when discrete graphic card is configured on shipped machine

Standard Features and Configurable Modules

AT A GLANCE

- Windows 10 Pro, Windows 10 Home or FreeDos 2.0
- Intel® H370 chipset supporting Intel® 8th and 9th processors featuring Intel® UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11ac (1x1) WiFi and Bluetooth® 4.2 Combo
- Up to 32GB DDR4-2666 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (either dTPM or fTPM)¹
- Supports both Hard Disk Drives and SATA TLC / M.2 PCIe NVMe Solid State Drives
- Audio in, Audio out and Mic in support 5.1 channel
- 8 USB Ports (including 4 USB 3.1 Gen1 ports)
- 180W/310W 90% HE power supply
- Security cable lock supported (sold separately)
- Protected by HP Services; terms and conditions vary by country; certain restrictions and exclusions apply
- Dust filter available

TPM feature will not be supported on machine pre-configured with FreeDOS In cases, machines pre-configured with Windows OS might ship with TPM turned off

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Modules

PRODUCT NAME

HP 290 G2 Microtower Business PC

OPERATING SYSTEM

Preinstalled Windows 10 Pro 64*

Windows 10 Home 64*

Pre-installed (other) FreeDOS 2.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/

PROCESSORS

Intel® Celeron® Processors2,3

CPU Intel Celeron G4900 Dual Core 3.1GHz 2400MHz 54W (3.1 GHz, 2 MB cache, 2 cores) CPU Intel Celeron G4930 Dual Core 3.2GHz 2400MHz 54W (3.2GHz, 2 MB cache, 2 cores)

Intel® Pentium® Processors^{2,3}

CPU Intel Pentium G5400 Dual Core 3.7GHz 2400MHz 54W (3.7 GHz, 4 MB cache, 2 cores) CPU Intel Pentium G5500 Dual Core 3.8GHz 2400MHz 54W (3.8 GHz, 4 MB cache, 2 cores)

Intel® Pentium Gold®2,3

CPU Intel Pentium G5420 Dual Core 3.8GHz 2400MHz 54W (3.8GHz, 4 MB cache, 2 cores) CPU Intel Pentium G5600 Dual Core 3.9Ghz 2400MHz 54W (3.9 GHz, 4 MB cache, 2 cores) CPU Intel Pentium G5620 Dual Core 3.8GHz 2400MHz 54W (3.8GHz, 4 MB cache, 2 cores)

Intel 8th Processors

Intel® Core™ i3^{2,3}

CPU Intel Core i3-8100 Quad Core 3.6GHz 2400MHz 65W (3.6 GHz, 6 MB cache, 4 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-8400 6C 2.8GHz 2666MHz 65W (2.8GHz, turbo up to 4GHz, 9 MB cache, 6 cores) CPU Intel Core i5+ (Core i5 and Intel® Optane™ Memory⁴)

i5-8400 6C 2.8GHz 2666MHz 65W (2.8GHz, turbo up to 4GHz, 9 MB cache, 6 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-8500 6C 3.0GHz 2666MHz 65W (3GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores)

CPU Intel Core i5+ (Core i5 and Intel® Optane™ Memory⁴)

i5-8500 6C 3.0GHz 2666MHz 65W (3GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores)

Intel® Core™ i7^{2,3}

CPU Intel Core i7-8700 6C 3.2GHz 2666MHz 65W (3.2GHz, turbo up to 4.6GHz, 12 MB cache, 6 cores) CPU Intel Core i7+ (Core i7 and Intel® Optane™ Memory⁴)

i7-8700 6C 3.2GHz 2666MHz 65W (Coffee Lake-S) (3.2GHz, turbo up to 4.6GHz, 12 MB cache, 6 cores)

Intel 9th Processors

Intel® Core™ i3^{2,3}

CPU Intel Core i3-9100 4C 3.6GHz 2400MHz 65W (3.6GHz, turbo up to 4.2GHz, 6 MB cache, 4 cores) CPU Intel Core i3-9300 4C 3.7GHz 2400MHz 62W (3.7GHz, turbo up to 4.3GHz, 8 MB cache, 4 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-9400 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.7GHz, 9 MB cache, 6 cores)*



Standard Features and Configurable Modules

CPU Intel Core i5-9400F 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.1GHz, 9 MB cache, 6 cores) CPU Intel Core i5-9500 6C 3GHz 2666MHz 65W (3GHz, turbo up to 4.4GHz, 9 MB cache, 6 cores) CPU Intel Core i5-9500F 6C 3GHz 2666MHz 65W (3GHz, turbo up to 4.4GHz, 9 MB cache, 6 cores) CPU Intel Core i5-9600 6C 3.1GHz 2666MHz 65W (3.1GHz, turbo up to 4.6GHz, 9 MB cache, 6 cores)

Intel® Core™ i7^{2,3}

CPU Intel Core i7-9700 8C 3GHz 2666MHz 65W (3GHz, turbo up to 4.7GHz, 12 MB cache, 8 cores)

2.Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel 8th or 9th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

3. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance. 4 Intel® Optane™ memory (cache) is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.

*NOTE: Only available on selected region

CHIPSET

Intel® H370 Chipset

GRAPHICS

Integrated5,6

Intel® UHD

Graphics 630 (integrated on 8 th Core i7/i5/i3 processors and 9th i5 processors)

Intel® UHD

Graphics 610 (integrated on 8th and 9th Pentium and Celeron)

Discrete Graphics

AMD Radeon™ R7 430 2GB PCIe x16 GFX AMD Radeon™ 520 1GB GFX NVIDIA® GeForce® GT730 1GB GFX NVIDIA® GeForce® GT730 2GB GFX NVIDIA® GeForce® GT1060 3GB GFX* NVIDIA® GeForce® GT1060 6GB GFX* NVIDIA® GeForce® GTX 1650 4GB*

5. HD content required to view HD images.

6. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

NOTE*: Available for specific region.



Standard Features and Configurable Modules

MEMORY⁷

Form Factor	Туре	Maximum	# of Slots
Microtower	DDR4 2666 (Transfer rates up	32 GB capacity	2 DIMM

to 2666 MT/s)

4GB DDR4-2666 UDIMM NECC (1x4GB) 8GB DDR4-2666 UDIMM NECC (1x8GB) 8GB DDR4-2666 UDIMM NECC (2x4GB) 16GB DDR4-2666 UDIMM NECC (1x16GB) 16GB DDR4-2666 UDIMM NECC (2x8GB)



^{7.} Memory modules support data transfer rates up to 2666 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

Standard Features and Configurable Modules

STORAGE⁸

SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive 128GB 2.5" TLC SSD 256GB 2.5" TLC SSD

Solid State Drives

128GB M.2 NVMe 256GB M.2 NVMe 512GB M.2 NVMe

SD Card Reader⁹

SD/SDHC/SDXC SD Card Reader

Intel Optane Memory¹⁰

SSD Intel 16GB 2280 Optance Memory

- 8. For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.
- 9. Card sold separately
- 10. Optional per configuration

OPTICAL DISC DRIVES¹¹

DVD-ROM 9.5mm
DVD-Writer 9.5mm*

11. Optical drives are optional or add on features. Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives.

NETWORKING12

Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

Wi-Fi and Bluetooth®

802.11ac (1x1) WiFi and Bluetooth® 4.2 Combo

12. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.



Standard Features and Configurable Modules

AUDIO / MULTIMEDIA

Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out / Mic-in jacks (3.5mm)

KEYBOARDS AND POINTING DEVICES¹³

Keyboard

USB Business Slim Wired Keyboard HP USB Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) Business Slim PS/2 Wired Keyboard No KB Option

Mouse

Antimicrobial USB Mouse (China)
HP Optical USB Mouse
Universal Wired Mouse USB
USB Hardened Mouse (India)
HP PS/2 Mouse (for machine configured with PS/2 port)
No Mouse Option

13. Keyboards and mouse are optional or add-on features.

PORTS

Front

Slim-height Bay - supporting an optical disk drive (optional)
Power Button
Combo jack, Headphone / Microphone
SD Card Reader
(2) USB 3.1 Gen1 Port
HDD LED Light

Not Shown

- (1) PCI Express x16
- (1) PCI Express x1 Accessory slot
- (1) Full-height PCI (Optional)
- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage



Standard Features and Configurable Modules

Rear

Audio Mic in

Audio Line out

Audio Link in

HDMI Port1

VGA Port1

Serial Port (optional, and available on legacy PCA only)

Standard lock slot

(2) USB 2.0 port

RJ-45 Network Connector

(2) USB 3.1 Gen1 Port and (2) USB 2.0 Port

Power Cord Connector

Padlock loop

Not Shown

- (2) PS/2 Port (optional, and available on legacy PCA only)
- (1) Parallel Port (Optional via PCIex1 slot)

1: Port will be covered up when discrete graphic card is configured on shipped machine

BAYS

- (1) 9.5mm external slimline ODD bay (optional)
- (1) 3.5" internal HDD bay
- (1) 3.5 or 2.5" internal HDD bay (share bay)

ENVIRONMENTAL AND INDUSTRY

Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® EPEAT® registered in the United States.* See http://www.epeat.net for registration status in your country.		
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".		
	Energy Consumption (in accordance with US ENERGY STAR® test			
	method)	115VAC, 60Hz 230VAC, 50Hz 100VAC, 60Hz		
	Normal Operation (Short idle)	12.97	13.03	13.39
	Normal Operation (Long idle)	10.64	10.72	10.46
	Sleep	0.78	0.76	0.77



Standard Features and Configurable Modules

Off	offered within the model f Logo are compliant with th (EPA) ENERGY STAR® speci offer ENERGY STAR® comp is for a typically configured supply, and a Microsoft Wi	d PC featuring a hard disk di ndows® operating system.	ed with the ENERGY STAR® ental Protection Agency a model family does not nergy efficiency data listed rive, a high efficiency power	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	44.23	44.43	45.66	
Normal Operation (Long idle)	36.28	36.56	35.67	
Sleep	2.66	2.59	2.63	
Off	*NOTE: Heat dissipation is service level is attained fo		1.43 easured watts, assuming the	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	3.6		26.5	
Fixed Disk – Random writes	3.6		26.5	
Longevity and Upgrading	"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. "This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium • "• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard, s www.epeat.net * • Plastics parts weighing over 25 grams used in the product are market per IS011469 and IS01043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 94.4% recycle-able when properly disposed of at end life."		tained in the product may	
Batteries				
Additional Information			the Waste Electrical and 2/96/EC. a Proposition 65 (State of orcement Act of 1986). 1680 (EPEAT) standard, see in the product are marked	



Standard Features and Configurable Modules

Packaging Materials	External:	PAPER/Corrugated	
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	
		PLASTIC/Polyethylene low density - LDPE	
	The plastic packaging material contains at least 50% recycled content.		
	The corrugated paper packaging materials contains at least 75% recycled content.		
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):		ment at
	 Cert reta Cad Chlo Forr Halo Leac 	estos ain Azo Colorants ain Brominated Flame Retardants – may not be used as fl rdants in plastics mium orinated Hydrocarbons orinated Paraffins maldehyde ogenated Diphenyl Methanes d carbonates and sulfates d and Lead compounds	lame
	 Mer Nick be f Ozo Poly Poly Poly Poly Volu Rad 	curic Oxide Batteries cel – finishes must not be used on the external surface decrequently handled or carried by the user. ne Depleting Substances brominated Biphenyls (PBBs) brominated Biphenyl Ethers (PBBEs) brominated Biphenyl Oxides (PBBOs) brominated Biphenyl (PCB) brominated Terphenyls (PCT) browinyl Chloride (PVC) – except for wires and cables, has be untarily removed from most applications. ioactive Substances utyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBT)	en
Packaging Usage	packaging: Elim cadi Elim mat Des Max pacl Use mat Red effic	ninate the use of heavy metals such as lead, chromium, menium in packaging materials. Sinate the use of ozone-depleting substances (ODS) in pacerials. Sign packaging materials for ease of disassembly. Simize the use of post-consumer recycled content materials aging materials. Sign packaging materials for ease of disassembly. Simize the use of post-consumer recycled content materials aging materials. Sign packaging materials are materials such as paper and erials. Suce size and weight of packages to improve transportations in the packaging materials are marked according to ISO 1146.	ercury and ckaging als in d corrugated on fuel



Standard Features and Configurable Modules

	End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
		The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
	HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
	Information	Global Citizenship Report
		http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
		Eco-label certifications
		http://www8.hp.com/us/en/hp-
		information/environment/ecolabels.html
		ISO 14001 certificates:
		http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
*EDEAT® rogic	torod whore applicable EDEA	Tregistration varies by country. See www.eneat.net for registration status by country

*EPEAT® registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe™ 11

Productivity

Buy Office (sold separately) Dropbox¹²

ODD Playback and TV Tuners

Power Media Player 14 for HP with DVD (ODD SKU only)¹³

Movies

Netflix14

App Stores and Content Purchasing

Amazon¹⁴

HP Utilities and Support

HP Documentation HP JumpStart HP Audio Switch HP Support Assistant¹⁵

BTB

HP Setup Integrated 00BE

Hardware Enabling Drivers or software utility

HP System Event Utility

*NOTE: Available for LA region only.

- 11. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration
- 12. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.
- 13. Actual speeds may vary. Don't copy copyright-protected materials
- 14. Internet access required and not included.
- 15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience
- 17. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Print times and connection speeds may vary.

POWER SUPPLY¹⁶

180 W

ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V

310 W

SFF ENTL EPA90 (Gold) Full range 115V/230V

16. All power supplies are not available in every region.

DIMENSIONS AND WEIGHT



Standard Features and Configurable Modules

Dimensions

6.69 x 13.3 x 10.79 in (170 x 338 x 274 mm)

Weight

11.9 lbs / 5.4 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
 is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
 enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 32° to 104° F (0° to 40° C)¹⁷

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 0% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 10,000 ft (3048 m)

Non-operating: 30,000 ft (9144 m)

17. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Standard Features and Configurable Modules

SERVICE AND SUPPORT

On-site Warranty 1: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day 2 service for parts and labor and complimentary limited technical support.3 Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.4 To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. **NOTE 3:** Technical support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

GRAPHICS

	Multimode capable; supports HDCP, DisplayPort™ Audio (2 streams), HBR2 link rates and		
DisplayPort™	Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)		
Memory	Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.		
Maximum Graphics Memory	Windows 10: >4 GB		
Maximum Color Depth	32 bits/pixel		
	8 th and 9 th Generation Intel [®] Core Processors		
Graphics/Video API Support	With Intel® UHD Graphics 630		
Crapines, viaco in i sappore	8 th and 9 th Generation Pentium [®] G5400 and Celeron [®] G4900,		
	With Intel® UHD Graphics 610		
	Supported Display Resolutions and Refresh Rates		
	800x600 @ 60 Hz		
	1024x768 @ 60 Hz		
	1152x864 @ 60 Hz		
	1280x600 @ 60 Hz		
	1280x720 @ 60 Hz		
	1280x800 @ 60 Hz		
	1280x960 @ 60 Hz		
Resolution/ Refresh Rates	1280x1024 @ 60 Hz		
Resolution, Refresh Rates	1360x768 @ 60 Hz		
	1366x768 @ 60 Hz		
	1400x1050 @ 60 Hz		
	1440x900 @ 60 Hz		
	1600x900 @ 60 Hz		
	1600x1200[1] @ 60 Hz		
	1680x1050 @ 60 Hz 1920x1080 @ 60 Hz		

Note: The actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort™ connector.



Technical Specifications - Graphics

NVIDIA® GeForce® GTX 1060 3GB Graphics Card

Engine Clock 1506 MHz
Memory Clock 4004 MHz
Memory Size(width) 3GB(192-bit)

 Memory Type
 128M x 32 GDDR5 @6pcs

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(HDMI)
 4096x2160@60Hz

 Max. Resolution(DP)
 5120x3200@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DVI-D+HDMI+DPx3

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <120W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® GTX 1060 6GB Graphics Card

Engine Clock 1506 MHz
Memory Clock 4004 MHz
Memory Size(width) 6GB(192-bit)

 Memory Type
 256M x 32 GDDR5 @6pcs

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(HDMI)
 4096x2160@60Hz

 Max. Resolution(DP)
 5120x3200@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DVI-D+HDMI+DPx3

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <120W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® GTX 1650 4GB Graphics Card

Engine Clock 1665 MHz
Memory Clock 4000 MHz
Memory Size(width) 4GB(128-bit)

 Memory Type
 256M x 32 GDDR5 @4pcs

 Max. Resolution(HDMI)
 4096 x 2160 x 24bpp @ 60 Hz

 Max. Resolution(DVI)
 2560 x 1600 x 24bpp @ 60 Hz

Multi Display Support 2 displays

HDCP Compliance yes

Rear I/O connectors(bracket) HDMI + DVI



Technical Specifications - Graphics

Cooling(active/passive) Active fan-sink

Total power consumption(W) <75W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® GT730 1GB Graphics Card

Engine Clock902 MHzMemory Clock1250 MHzMemory Size(width)1GB(64-bit)

 Memory Type
 128M x 32 GDDR5 @2pcs

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(HDMI)
 4096x2160@24Hz

Multi Display Support 2 displays

HDCP Compliance yes

Rear I/O connectors(bracket) DVI+HDMI

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <35W

PCB form-factor with bracket LP PCB with FH/LP bracket

NVIDIA® GeForce® GT 730 2GB Graphics Card

Engine Clock902 MHzMemory Clock1250 MHzMemory Size(width)2GB(64-bit)

 Memory Type
 256M x 32 GDDR5 @2pcs

 Max. Resolution(DVI)
 2560x1600@60Hz

 Max. Resolution(DP)
 4096x2160@60Hz

Multi Display Support2 displaysHDCP Complianceyes

Rear I/O connectors(bracket) DVI+DP

Cooling(active/passive) Active fan-sink(Active cooling with dynamic speed)

Total power consumption(W) <35W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD Radeon™ R7 430 2GB Graphics Card

Engine Clock 780 MHz
Memory Clock 1100 MHz
Memory Size(width) 2GB(128-bit)

Memory Type 128M x 32 GDDR5 @4pcs

Max. Resolution(VGA) 2048x1536



Technical Specifications - Graphics

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance yes

Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD Radeon™ 520 1GB Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)1GB(32-bit)

Memory Type 256M x 32 GDDR5

Max. Resolution(VGA) 2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance yes **Rear I/O connectors(bracket)** VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications -Storage

STORAGE

HP 2 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 2 TB

Rotational Speed 7,200 rpm

Interface SATA 6Gb/s NCQ

Buffer Size 64 MB

 Logical Blocks
 3,907,029,168

 Seek Time
 Read: <8.5 ms</td>

 Notice = 0.5 ms
 Notice = 0.5 ms

Write: <9.5 ms

 Height
 1.028 in/26.11 mm

 Width
 4.0 in/101.6 mm

Operating Temperature 32° to 140° F (0° to 60° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 1 TB

Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32 MB

Logical Blocks 1,953,525,168

Seek Time Single Track: 2.0 ms
Average: 11 ms

Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 500 GB
Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32 MB

Logical Blocks 1,953,525,168
Seek Time Single Track: 2.0 ms



Technical Specifications -Storage

Average: 11 ms Full-Stroke: 21 ms

1 in/2.54 cm Height

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

SATA/ATAPI Interface type

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Read Speeds DVD-R DL Up to 6X

Up to 8X DVD+R Up to 8X DVD+RW DVD+R DL Up to 6X DVD-R Up to 8X **DVD-RW** Up to 6X Up to 24X CD-R CD-RW Up to 10X DVD-RW. DVD+RW Up to 8X DVD-R DL. DVD+R DL Up to 8X DVD+R, DVD-R Up to 8X DVD-ROM DL. DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X

Access time

(typical reads, including

settling)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Up to 24X

Stop Time 6 seconds (typical)

Source Slimline SATA DC power receptacle Power

CD-RW

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

SATA/ATAPI Interface type

Up to 8.5 GB DL or 4.7 GB standard Disc recording capacity



Technical Specifications -Storage

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Read Speeds DVD-R DL Up to 6X

Up to 8X DVD+R DVD+RW Up to 8X DVD+R DL Up to 6X DVD-R Up to 8X DVD-RW Up to 6X CD-R Up to 24X CD-RW Up to 10X DVD-RW, DVD+RW Up to 8X DVD-R DL, DVD+R DL Up to 8X DVD+R, DVD-R Up to 8X DVD-ROM DL. DVD-ROM Up to 8X CD-ROM. CD-R Up to 24X CD-RW Up to 24X

Access time Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) (typical reads, including Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

settling) Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

128 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity128GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1400MB/sMaximum Sequential WriteUp to 395MB/sLogical Blocks250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications -Storage

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity256 GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity512 GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB 2.5in SATA Three Layer Cell SSD

Drive Weight <50g
Capacity 128GB
Height 7mm
Length 100.45mm
Width 69.85mm
Interface SATA 3.0 (6Gb/s)

interrace SATA 3.0 (000/5)

Performance Up to Random Read/Write = 70K/40K IOPS



Technical Specifications -Storage

Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 380MB/sLogical Blocks250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB 2.5in SATA Three Layer Cell SSD

 Drive Weight
 <62g</td>

 Capacity
 256GB

 Height
 7mm

 Length
 100.45mm

 Width
 69.85mm

 Interface
 SATA 3.0 (6Ch)

Interface SATA 3.0 (6Gb/s)

Performance Up to Random Read/Write = 55K/68K IOPS

Maximum Sequential ReadUp to 530MB/sMaximum Sequential WriteUp to 450MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications - Audio

HIGH DEFINITION AUDIO

Type Integrated

HD Stereo Codec Realtek ALC3601

Audio I/O Ports Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

HD Audio Codec Realtek ALC3601

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/

48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC

Wavetable Syntheses Yes
Analog Audio Yes
of Channels on Line-Out Stereo
Internal Speaker Yes

External Speaker Jack 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

Technical Specifications - Power

POWER SUPPLY

Operating Voltage Range 90 - 264 VAC Rated Voltage Range 100-240V AC **Rated Line Frequency** 50/60 HZ **Operating Line Frequency** 47 - 63 Hz **Rated Input Current** 180W: <2.3A; 310W: <4A

Rated Input Current with Energy Efficient* Power

Supply

180W active PFC

87/90/87% efficient at 20/50/100% load (115V) 88/91/88% efficient at 20/50/100% load (230V);

310W active PFC

87/90/87% efficient at 20/50/100% load (115V) 88/91/88% efficient at 20/50/100% load (230V)

DC Output +12.1V

Current Leakage (NFPA 99:

2102)

Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Power Supply Fan 70*25mm (linear type)



Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS

Chassis (W x H x D) 6.69 x 13.3 x 10.79 in (170 x 338 x 274 mm)

System Volume 960.06cu in

15.76L

System Weight* 11.9 lbs / 5.4 kg

Max Supported

Weight (desktop

orientation) N/A

Tower Stand

(**H x W x D**) 13.42 x 6.69 x 10.92 in (340.8 x 170 x 277.5 mm)

Packaged 11.46 x 15.35 x 19.65 in (H x W x D) 291 x 390 x499 mm

Shipping Weight 17.64lb / 8 kg
Palletization 6 units per layer
Profile 7 layer max

42 per pallet Footprint

-85.31x39.37x47.24 in (2167 x 1000 x1200 mm)



Technical Specifications-Miscellaneous Features

ADDITIONAL FEATURES

Description

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted



Technical Specifications- Networking

NETWORKING

10/100/1000 NIC	Ethernet Features		peration (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-
		21-30) 1000 Mbit/s clauses 40) Auto-Negot	operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses diation (Automatic Speed Selection) Operation at all Speeds, Half Duplex operation at 10 and
	Power Management	Situation-so	ant – multiple power modes ensitive features reduce power consumption nk down power saving for reducing link down power on
	Performance Features	Protocol Of	_
	Manageability	Microsoft Wonly) PXE 2.1 Rer Statistics G (802.3x, cla	athering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB
	Interface	PCIe + SMBı	JS
	NIC Device Driver Name	PCIe GBE Et	hernet Family Controller
Realtek 802.11ac (1x1) W	iFi and Bluetooth® 4.2	Combo *	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac		
Interoperability	Wi-Fi certification		
Frequency Bands	802.11b/g/n		• 2.402 – 2.482 GHz
	802.11a/n		 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz



	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
Dala Kales	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
•	AES-CCMP: 128 bit in hardware
	802.1x authentication
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	802.11b : +14dBm minimum
	802.11g: +12dBm minimum
	802.11a: +12dBm minimum
	• 802.11n HT20(2.4GHz): +12dBm minimum
	• 802.11n HT40(2.4GHz): +12dBm minimum
	 802.11n HT20(5GHz): +10dBm minimum
	• 802.11n HT40(5GHz): +10dBm minimum
	• 802.11ac VHT80(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode2.0 W
	Receive mode1.6 W
	 • Idle mode (PSP)180 mW(WLAN Associated)
	• Idle mode50 mW(WLAN unassociated)
	• Connected Standby 10mW
	• Radio disabled8 mW
	ACPI and PCI Express compliant power management



Receiver Sensitivity³	 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications		
Form Factors	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)		
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
HP Integrated Module with Blueto	ooth 4.0/4.1/4.2 Wireless Technolog	у	
Bluetooth® Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE : 1 Mbps data rate; throughpu Legacy : Synchronous Connection	it up to 0.2 Mbps Oriented links up to 3, 64 kbps, voice channels	



	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 4 dBm for BR and EDR.
Receiver Sensitivity Legacy	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support
Certifications Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

^{1.} Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

^{2.} The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.



- 3. Check latest software/driver release for updates on supported security features.4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.



After-Market Options (availability may vary by region)

AFTER MARKET OPTIONS

Туре	Description	Part #
Memory	HP 4GB DDR4-2666 DIMM	3TK85AA
	HP 8GB DDR4-2666 DIMM	3TK87AA
	HP 16GB DDR4-2666 DIMM	3TK83AA
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP Turbo Drive Gen2 256GB M.2 SSD Drive	1CA51AA
	Intel Optane Memory 16GB (cache) ****	1WV97AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	NVIDIA® GT 730 2GB DP Card	Z9H51AA
	AMD Radeon™ R7 430 Card	1MX32AA
Security	HP Business PC Security Lock V2 Kit	N3R93AA
Jecurity	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP USB to Serial Adapter	J7B60AA
	HP HDMI Standard Cable Kit	T6F94AA
	HP USB to Serial Port Adapter	J7B60AA
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
put	HP USB Hardened Mouse	P1N77AA
	HP USB Keyboard	QY776AA
	HP PS/2 Business Slim Keyboard	N3R86AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	T4E61AA
	HP USB Business Speakers v2	N3R89AA



Change Log

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Date of change:	Version History:	Change	Description of change:
March 18, 2019	From v1 to v2	Update	Processor i5-9400 removed
March 21, 2019	From v2 to v3	Update	Processor i5-9400 put back on
April 23, 2019	From v3 to v4	Refresh	Processors under embargo added to official QS refresh
May 14, 2019	From v4 to v5	Update	i7-9700/i5-9400F/i5-9500F processors added
July 2, 2019	From v5 to v6	Update	CPU Intel Core i3-9300, i5-9600 and Pentium Gold G5620 added and
			Intel® Core™ i7-9700 removed to/from processors section
August 1, 2019	From v6 to v7	Update	GTX1650 added to graphics
			Pentium G5600 added to processors.
August 16, 2019	From V7 to V8	Update	PCIe x1 (2.0) corrected
			AMD Radeon 520 1GB added
			Standard security lock slot upgrade @ call outs
August 21, 2019	From V8 to V9	Update	Intel® Core™ i7-9700 put back in to processors section
October 3, 2019	From V9 to V10	Update	Miscellaneous Features section added
November 27, 2019	From V10 to V11	Update	NVIDIA® GeForce® GT1060 6GB GFX reference added to footnote
December 2, 2019	From V11 to V12	Update	NVIDIA® GeForce® GT1060 3GB GFX reference added to footnote
February 27, 2020	From V12 to V13	Update	Processor i7-9700 Turbo boost tech spec corrected

